

| Ref # | Hits  | Search Query   | DBs  | Default Operator | Plurals | Time Stamp       |
|-------|-------|--|--|------------------|---------|------------------|
| L1    | 11366 | 257/81,99,177-181,584,625,675,688,689,704-707,712,722,796.ccls.              | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:07 |
| L2    | 5243  | 1 and (slug ((heat thermal) near (sink spreader dissipat\$3)))               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:45 |
| L3    | 1130  | 2 and ((cavity recess groove open\$3 hols\$1) with (chip die))               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:12 |
| L4    | 1020  | 2 and ((cavity recess groove open\$3 hols\$1) with (chip die))               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:13 |
| L5    | 1315  | 2 and ((cavity recess groove open\$3 hole\$1) with (chip die))               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:13 |
| L6    | 123   | 2 and ((cavity recess groove open\$3 hole\$1) with (chip die) with thick\$4) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:33 |
| L7    | 419   | 2 and ((cavity recess groove open\$3 hole\$1) same (chip die) same thick\$4) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:38 |
| L8    | 2     | 7 and ((downset near leg\$1) same (depth thick\$4))                          | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:37 |
| L9    | 2     | 7 and (downset near leg\$1)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR               | ON      | 2005/10/05 12:47 |

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| L10 | 469    | 2 and ((cavity recess groove open\$3 hole\$1) same (chip die) same (depth thick\$4))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:45 |
| L11 | 145    | 10 and (corner\$1 notch\$2)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:46 |
| L12 | 227823 | (slug ((heat thermal) near (sink spreader dissipat\$3)))                              | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:27 |
| L13 | 5725   | 12 and ((cavity recess groove open\$3 hole\$1) same (chip die) same (depth thick\$4)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:46 |
| L14 | 1827   | 13 and (corner\$1 notch\$2)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:46 |
| L15 | 6078   | 12 and ((cavity recess groove open\$3 hole\$1) same (chip die) same (depth thick\$4)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:52 |
| L16 | 1934   | 15 and (corner\$1 notch\$2)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:56 |
| L17 | 3      | 16 and (downset near leg\$1)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:47 |
| L18 | 24     | 16 and downset  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:56 |

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| L19 | 13    | 15 and ((corner\$1 notch\$2) same downset)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:53 |
| L20 | 24701 | 12 and ((cavity recess groove open\$3 hole\$1) and (chip die) and (depth thick\$4)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:54 |
| L21 | 23    | 20 and ((corner\$1 notch\$2) same downset)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:55 |
| L22 | 69790 | ((cavity recess groove open\$3 hole\$1) same (chip die) same (depth thick\$4))      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:21 |
| L23 | 17    | 22 and ((corner\$1 notch\$2) same downset)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 12:55 |
| L24 | 18007 | 22 and (corner\$1 notch\$2)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:22 |
| L25 | 35    | 24 and downset  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:22 |
| L26 | 6418  | 438/22,24,117,122-127.ccls.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:15 |
| L27 | 4643  | 26 and (cavity recess groove open\$3 hole\$1)                                       | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:22 |

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| L28 | 917 | 27 and (corner\$1 notch\$2)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:22 |
| L29 | 19  | 28 and downset  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT<br>; IBM_TDB | OR | ON | 2005/10/05 13:23 |
| L30 | 9   | ("4748538"   "5949137"   "6191360"  <br>"6271058"   "6462410"   "6483169"  <br>"6512675"   "6525420"   "6538320").PN.   | US-PGPUB;<br>USPAT;<br>USOCR                                       | OR | ON | 2005/10/05 13:24 |
| L31 | 0   | (slug ((heat thermal) near (sink spreader<br>dissipat\$3))) AND (rectangular NEAR<br>shape) AND surface\$1 AND (notch\$2<br>corner\$1) AND (three NEAR downset<br>NEAR leg\$1) AND (cavity recess\$2 groove<br>open\$3 hole\$1) AND (chip die) AND<br>(depth thick\$4).CLM. | US-PGPUB;<br>USPAT   | OR | ON | 2005/10/05 13:31 |
| L32 | 0   | (slug ((heat thermal) near (sink spreader<br>dissipat\$3))) AND surface\$1 AND (notch\$2<br>corner\$1) AND (three NEAR downset<br>NEAR leg\$1) AND (cavity recess\$2 groove<br>open\$3 hole\$1) AND (chip die) AND<br>(depth thick\$4).CLM.                                 | US-PGPUB;<br>USPAT   | OR | ON | 2005/10/05 13:31 |
| L33 | 0   | (slug ((heat thermal) near (sink spreader<br>dissipat\$3))) AND (rectangular NEAR<br>shape) AND surface\$1 AND (notch\$2<br>corner\$1) AND (three NEAR downset)<br>AND (cavity recess\$2 groove open\$3<br>hole\$1) AND (chip die) AND (depth<br>thick\$4).CLM.             | US-PGPUB;<br>USPAT   | OR | ON | 2005/10/05 13:32 |